

ATP Industrial Grade DRAM Modules

ATP Electronics, Inc.

Targeted Product Portfolio, Engineered Specifically for Your Mission Critical Applications

Product	Category	Speed (MT/s)	Form Factor	Features
DDR4	LRDIMM/RDIMM UDIMM/UDIMM ECC SO-DIMM/SO-DIMM ECC Mini-RDIMM Mini-UDIMM ECC	2133 2400 2666	 Low profile Very Low Profile (VLP) options (VLP: 0.74" height) Ultra Low Profile (ULP) options (ULP: 0.7"~0.72" height) 	 Density: 4GB to 64GB Increased performance and bandwidth (up to 3200 MT/s) Decreased voltage for better power consumption Provides better reliability, availability and serviceability (RAS) and improves data integrity.
DDR3	LRDIMM/RDIMM UDIMM/UDIMM ECC SO-RDIMM SO-DIMM/SO-DIMM ECC mini-RDIMM mini-UDIMM ECC	1866 1600 1333 1066	(VLP: 0.74" height)	 Density: 1GB to 32GB 32GB to 64GB(LRDIMM) Chipkill support Fly-by command/address/control bus with on-DIMM termination. Higher bandwidth performance, effectively up to 1866 MT/s Better performance at low power; 1.5V (Normal) and 1.35V(Low Voltage)
DDR2	RDIMM UDIMM/UDIMM ECC SO-RDIMM SO-CDIMM SO-DIMM mini-RDIMM FB-UDIMM*	800 667 533 400	 Low Profile Very Low Profile (VLP) options (VLP:0.72"~0.74" height) 	 Density: 1GB to 8GB Chipkill support FB-DIMM Low power and low voltage options Apple FB-DIMM
DDR*	UDIMM/UDIMM ECC SO-CDIMM SO-DIMM	400 333 266	 Low Profile Very Low Profile (VLP) options (VLP:0.72"~0.74" height) 	Chipkill support Legacy system support
SDRAM*	SO-DIMM	PC 133 PC 100	• Low Profile	• Legacy system support

Product Portfolio	Category	Product	Features
Industrial Grade Family		DDR4 DDR3 DDR2 DDR* SDRAM*	 Extended temperature:-40°C ~ +95°C Controlled BOM and SPD
			 For mission critical industrial applications conformal coating

^{*} Available on a project basis.

ATP Products Distributed By:



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